

Product / Process Change Notification



N° 2017-051-A

Dear Customer,

Please find attached our INFINEON Technologies PCN:

Introduction of additional lead plating supplier for SOT packages and additional wafer test location

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before **7. June 2017**.
- Infineon aligns with the widely-recognized JEDEC STANDARD “**JESD46**“, which stipulates:
“**Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change.**”

Your prompt reply will help Infineon Technologies to assure a smooth and well executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.

Infineon Technologies AG
Postal Address Headquarters: Am Campeon 1-12, D-85579 Neubiberg, Phone +49 (0)89 234-0
Chairman of the Supervisory Board: Wolfgang Mayrhuber
Management Board: Dr. Reinhard Ploss (CEO), Dominik Asam, Dr. Helmut Gassel, Jochen Hanebeck
Registered Office: Neubiberg Commercial Register
Amtsgericht München HRB 126492

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► Products affected:

Please refer to affected product list 1_cip17051a

- Plating and Wafer Test: see *"Plating and Wafer Test affected products"* marked

- Wafer Test Transfer: see *"Wafer Test affected products"* marked

- Lead Plating Supplier: see *"Plating affected products"* marked

► Detailed Change Information:

Subject: Introduction of additional lead plating supplier for SOT packages and additional wafer test location

Reason: Expansion of wafer test and lead plating capacity.
Due to continuously raising demand for Infineon products, we are implementing wafer test facility in Infineon Kulim as additional wafer test location and WELNEW plating supplier as additional new lead plating supplier to assure continuity of supply and enable flexible manufacturing.

Description:

	<u>Old</u>	<u>New</u>
Wafer test location	<ul style="list-style-type: none">■ Infineon Technologies Austria AG, Villach, Austria	<ul style="list-style-type: none">■ Infineon Technologies Austria AG, Villach, Austria or <ul style="list-style-type: none">■ Infineon Technologies (Kulim) Sdn. Bhd, Malaysia
Lead Plating Supplier	<ul style="list-style-type: none">■ TECHNIC plating supplier	<ul style="list-style-type: none">■ TECHNIC plating supplier or <ul style="list-style-type: none">■ WELNEW plating supplier

► Product Identification:

Traceability assured via internal part number. No change in SP ordering number.

► Impact of Change:

Based on the qualification performed, Infineon does not see any negative impact on quality, function and reliability. No impact on fit and form.

► Attachments:

Affected product list 1_cip17051a
Qualification Report 2_cip17051a

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► Time Schedule:

■ Final qualification report:	30.05.2016 (2_cip17051a)
■ First samples available:	on request
■ Intended start of delivery:	01-Oktober-2017 or earlier after customer release

If you have any questions, please do not hesitate to contact your local Sales office.